



Copper (Cu) Wire Bondability  
Quick Summary

Tel (800) 776-9888 [www.TopLine.tv](http://www.TopLine.tv)  
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Combination Nbr	Silicon Die Pads	Lead Frame or Substrate	Type	Plating on bonding fingers	Bonding with Cu Wire	Bondability	Comments
1	Al	BT Strip	BGA	Ni/Au	Cu	NO	Recommend Pd/Cu (Palladium Copper Wire)
2	Cu	BT Strip	BGA	Ni/Au	Cu	NO	Recommend Pd/Cu and using some OSP on the copper pads
3	Al	Cu Leadframe	QFN	NiPdAu	Cu	YES	Very narrow bonding window. Suggested solution Pd/Cu bonding wire
4	Cu	Cu Leadframe	QFN	NiPdAu	Cu	Caution	This Combination is problematic. Use caution to control process window. Possible oxidation on bond pads
5	Al	Cu Leadframe	QFN	Spot Silver	Cu	YES	Stable process
6	Cu	Cu Leadframe	QFN	Spot Silver	Cu	Caution	This Combination is problematic. Use caution to control process window. Possible oxidation on bond pads